

0.65x0.35x0.2mm (0201) SMD CHIP LED LAMP

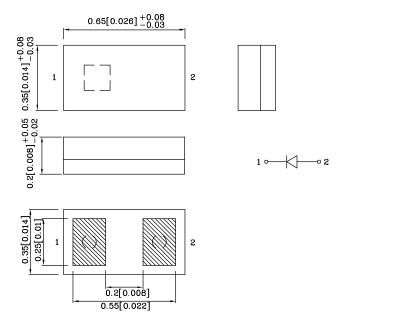
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 4,000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 2
- RoHS compliant





Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Orange (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	20	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA	
Power Dissipation	P_{D}	48	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	C	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics $(T_A=25^{\circ}C)$	Orange (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2.01	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.4	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =10mA)	λΡ	611*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) $(I_F=10\text{mA})$	λD	605*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	17	nm

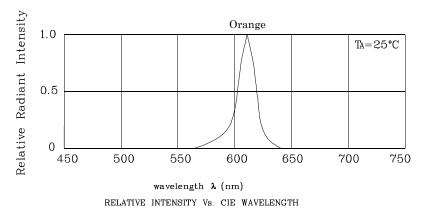
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous CIE127 (I _F =10 mo	7-2007* OmA)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMOR155W	Orange	AlGaInP	Water Clear	60 20*	148 49*	611*	140°

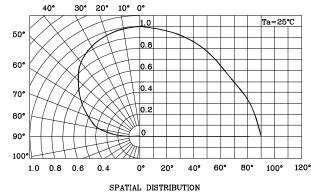
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Jan 23,2016

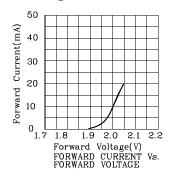


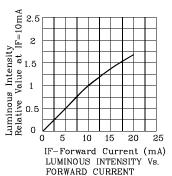


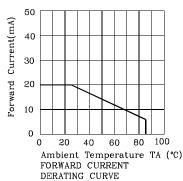


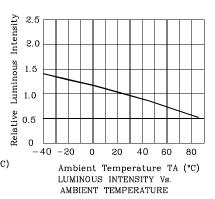


❖ Orange



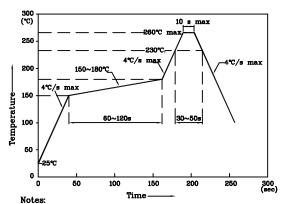






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

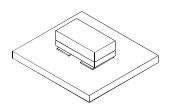


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

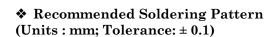


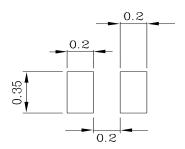


❖ The device has a single mounting surface. The device must be mounted according to the specifications.

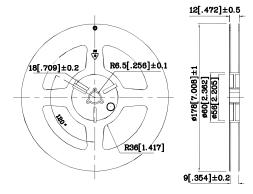


* Reel Dimension

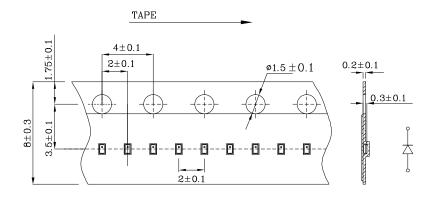




Mask open area ratio:80% Mask thickness:80~100um



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

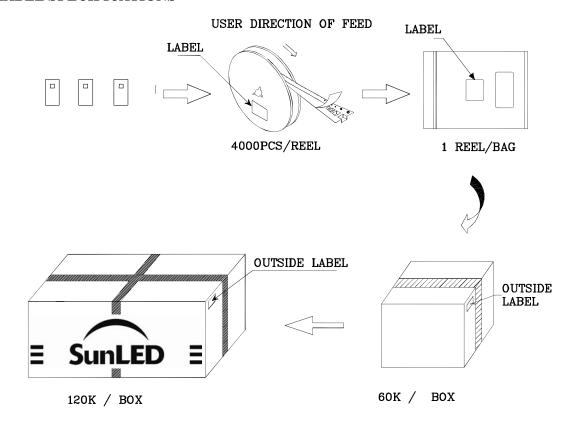
Note: Accuracy may depend on the sorting parameters.

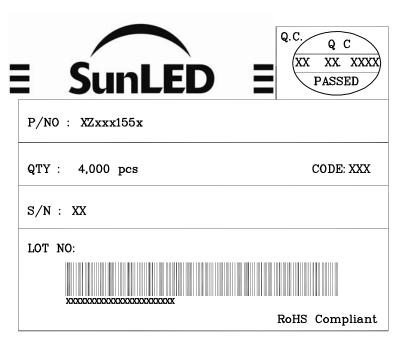


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PACKING & LABEL SPECIFICATIONS

www.SunLEDusa.com





TERMS OF USE

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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp Jan 23,2016

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